ESD/EMI Protection For Color Lcd Interfaces

EM2374K

IEC COMPATIBILITY

- IEC61000-4-2 (ESD) ±15kV (air), ±8kV (contact)
- IEC61000-4-4 (EFT): 40A - 5/50ns

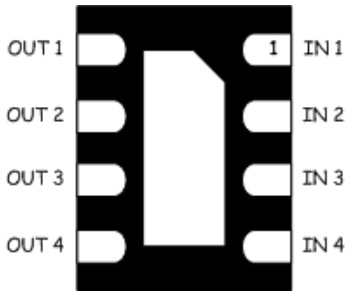
Feature

- TVS working voltage: 5V
- Resistor: 100Ω +/− 20%
- Typical Capacitance: 20pF (VR = 0V)
- Protection and filtering for four lines
- Solid-state technology
- RoHS Compliant
- Bidirectional EMI/RFI filter with integrated TVS for ESD protection
- Filter performance: 30dB minimum attenuation 1.8GHz to 2.5GHz

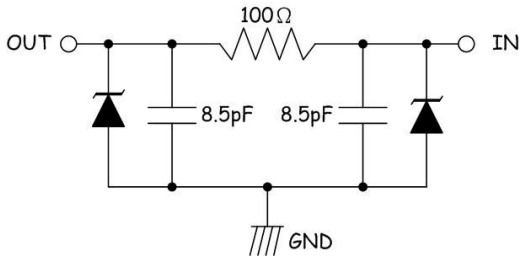
Applications

- Cell Phone CCD Camera Lines
- Color LCD Protection
- Clamshell Cell Phones

DFN-1714



Functional Diagram



Mechanical Data

- Nominal Dimensions: 1.7 x 1.35 x 0.50 mm
- Molding Compound Flammability Rating : UL 94V-O
- Quantity Per Reel : 3,000pcs
- Reel Size : 7 inch
- Lead Finish : Lead Free

Mechanical Characteristics

Symbol	Parameter	Value	Units
T_J	**Junction Temperature**	125	ºC
T_{OP}	**Operating Junction Temperature Range**	-40 to +85	ºC
T_{STG}	**Storage Temperature Range**	-55 to +150	ºC
T_L	**Soldering Temperature, T max = 10s**	260	ºC

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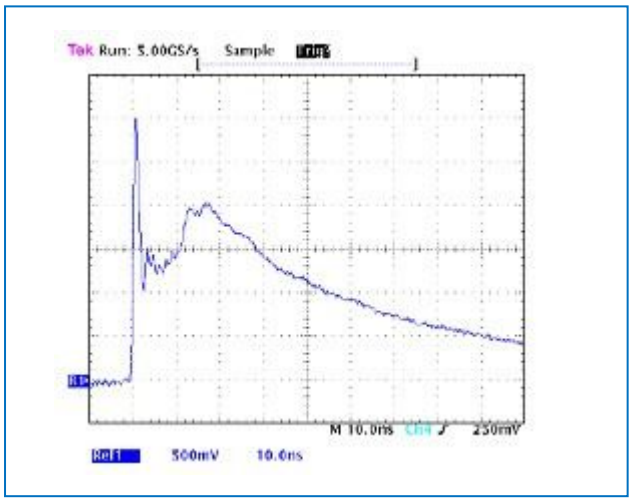
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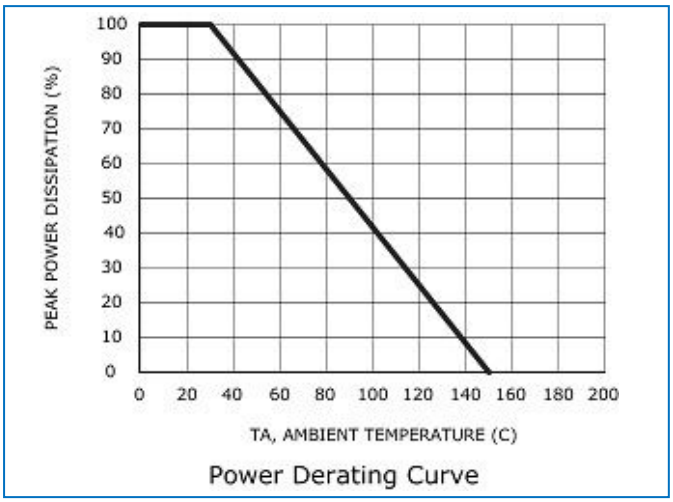
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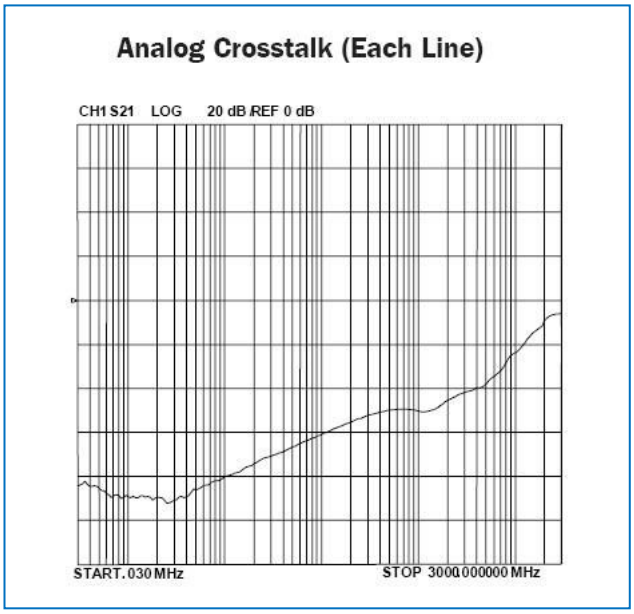
Electrical Characteristics (@ 25℃ Unless Otherwise Specified)

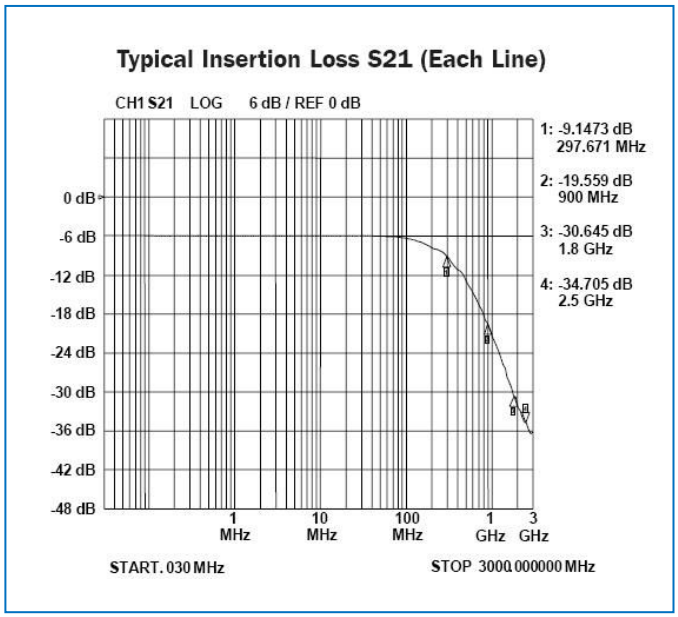
Part Number	Device Marking Code	V_{RMW} (V) (max.)	V_{BR} (V) (max.)	R (Ω) (Typ.)	F3dB (MHz) (Typ.)	F6dB (MHz) (Typ.)	I_R (uA) (max.)	C_T @0V (pF) (Typ.)	C_T @2.5V (pF) (Typ.)
EM2374K	K34	5.0	6.0	100	250	295	0.5	12.8	8.5

Characteristic Curves







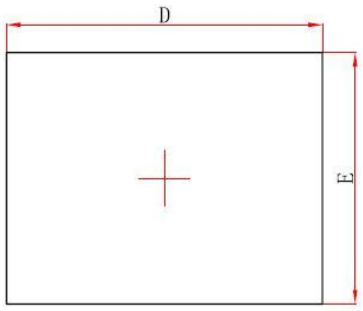


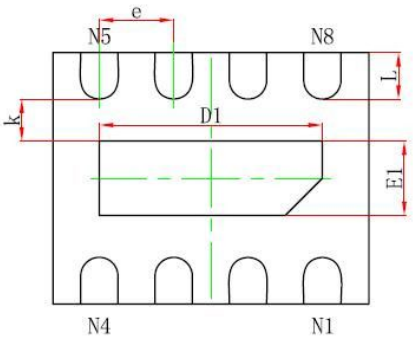
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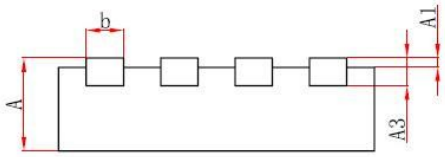
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DFN-1714 Package Outline & Dimensions

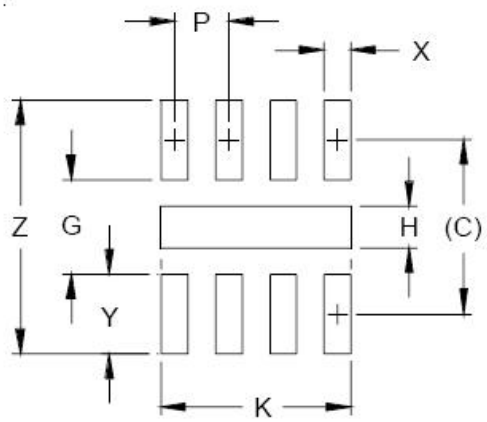






Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.450/0.550	0.550/0.650	0.018/0.022	0.022/0.026
A1	0.000	0.050	0.000	0.002
A3	0.150REF.		0.006REF.	
D	1.600	1.800	0.063	0.071
E	1.250	1.450	0.049	0.057
D1	1.100	1.300	0.043	0.051
E1	0.300	0.500	0.012	0.020
k	0.200MIN		0.008MIN	
b	0.150	0.250	0.006	0.010
e	0.400TYP.		0.016TYP.	
L	0.150	0.350	0.006	0.014

* SOLDERING FOOTPRINT



DIMENSIONS		
DIM	INCHES	MILLIMETERS
C	(.050)	(1.27)
G	.027	0.69
H	.012	0.30
K	.055	1.40
P	.016	0.40
X	.008	0.20
Y	.023	0.58
Z	.073	1.85

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